

✓ Search ...

PRODUCTS | APPLICATIONS | DESIGN SUPPORT | TRAINING | SAMPLE AND BUY | ABOUT US | CONTACT US | myMicrochip Login

# Product Change Notification - JAON-01ZFTR707

Date:	09 Sep 2016
Product Category:	Memory; Analog (Linear & Mixed Signal) AND Interface; Analog (Thermal, Power Management &
	Safety); 8-bit Microcontrollers
Notification subject:	CCB 2622 Final Notice: Qualification of G700 molding compound and 8600 die attach material for
Notification text:	all automotive products available in 8L DFN (2x3mm) package at NSEB assembly site. <b>PCN Status:</b> Final notification

# Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## Description of Change:

Qualification of G700 molding compound and 8600 die attach material for all automotive products available in 8L DFN (2x3mm) package at NSEB assembly site.

Pre Change: Using G770 molding compound and 8200T die attach material

Post Change:

Using G700 molding compound and 8600 die attach material.

# Pre and Post Change Summary:

	Pre Change	Post Change					
Assembly Site	NSEB assembly site	NSEB assembly site					
Assembly one		NOLD assembly site					
Wire material	Au wire	Au wire					
Die attach material	8200T	8600					
Molding compound material	G770	G700					
Lead frame material	EFTEC-64T	EFTEC-64T					

Impacts to Data Sheet: None

Change Impact: None

Reason for Change:

To improve productivity and standardization by using the best known material set for automotive products at the NSEB assembly site.

#### **Change Implementation Status:**

In Progress

## Estimated First Ship Date:

December 9, 2016 (date code: 1649)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### **Time Table Summary:**

	N	/lay	201	6	->	September 2016						December 2016					
Work Week	18	19	20	21		35	36	37	38	39		48	49	50	51	52	
Initial PCN Issue Date				х													
Qualification Report Availability							х										
Final PCN Issue Date							х										
Estimated Implementation Date													х				

#### Method to Identify Change:

Traceability code

#### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN # Qual Report.

#### **Revision History:**

May 27, 2016: Issued initial notification.

July 6, 2016: Re-issued the initial notification to notify all affected customers. September 9, 2016: Issued final notification. Attached the qualification report. Added estimated first ship date on December 2, 2016. Corrected a typographical error on the lead frame material on the pre and post change summary table from C194 to EFTEC-64T. Updated the reason for change.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN\_JAON-01ZFTR707\_Qual\_Report.pdf PCN\_JAON-01ZFTR707\_Affected\_CPN.pdf PCN\_JAON-01ZFTR707\_Affected\_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

# **Terms and Conditions:**

http://www.microchip.com/mymicrochip/NotificationDetails.aspx?pcn=JAON-01ZFTR70... 9/12/2016

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."



Products | Applications | Design Support | Training | Sample and Buy | About Us | Contact Us | Legal | Investors | Careers | Support

©Copyright 1998-2016 Microchip Technology Inc. All rights reserved. Shanghai ICP Recordal No.09049794 JAON-01ZFTR707 - CCB 2622 Final Notice: Qualification of G700 molding compound and 8600 die attach material for all automotive products available in 8L DFN (2x3mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-01ZFTR707
CATALOG_PART_NBR
24AA16-I/MC16KVAO
24AA16T-I/MC16KVAO
24LC64T-E/MC16KVAO
24LC64T-I/MC16KVAO
MCP4921-E/MCVAO
MCP4921T-E/MCVAO
MCP6002-E/MCVAO
MCP6002T-E/MCVAO
MCP9804-E/MCVAO
MCP9804T-E/MCVAO
PIC12F509T-I/MCVAO
PIC12F510-E/MCVAO